

EVVOSEMI[®]

THINK CHANGE DO



ESD



TVS



MOS



LDO



Diode



Sensor



DC-DC

Product Specification

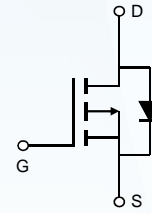
▶ Domestic	Part Number	AO4441
▶ Overseas	Part Number	AO4441
▶ Equivalent	Part Number	AO4441

EV is the abbreviation of name EVVO

-60V P-Channel MOSFET

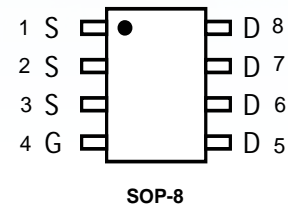
General Description

The AO4441 uses advanced trench technology to provide excellent $R_{DS(ON)}$, and ultra-low low gate charge. This device is suitable for use as a load switch or in PWM applications.



Features

- $V_{DS(V)} = -60V$
- $I_D = -4A$ ($V_{GS} = -10V$)
- $R_{DS(ON)} < 100m\Omega$ ($V_{GS} = -10V$)
- $R_{DS(ON)} < 130m\Omega$ ($V_{GS} = -4.5V$)



Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	-60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ^A	I_D	$T_A=25^\circ C$	-4
		$T_A=70^\circ C$	-3.1
Pulsed Drain Current ^B	I_{DM}	-20	A
Power Dissipation ^A	P_D	$T_A=25^\circ C$	3.1
		$T_A=70^\circ C$	2
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ C$

Thermal Characteristics					
Parameter		Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$t \leq 10s$	$R_{\theta JA}$	24	40	$^\circ C/W$
Maximum Junction-to-Ambient ^A	Steady-State		54	75	$^\circ C/W$
Maximum Junction-to-Lead ^C	Steady-State	$R_{\theta JL}$	21	30	$^\circ C/W$

-60V P-Channel MOSFET

 Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=-250\mu\text{A}$, $V_{GS}=0\text{V}$	-60			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-48\text{V}$, $V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			-1 -5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}$, $V_{GS}=\pm 20\text{V}$			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=-250\mu\text{A}$	-1	-2.1	-3	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS}=-10\text{V}$, $I_D=-4\text{A}$		80	100	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}$, $I_D=-3\text{A}$		102	130	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{DS}=-5\text{V}$, $I_D=-4\text{A}$		10		S
V_{SD}	Diode Forward Voltage	$I_S=-1\text{A}$, $V_{GS}=0\text{V}$		-0.77	-1	V
I_S	Maximum Body-Diode Continuous Current				-4	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}$, $V_{DS}=-30\text{V}$, $f=1\text{MHz}$		930	1120	pF
C_{oss}	Output Capacitance			85		pF
C_{riss}	Reverse Transfer Capacitance			35		pF
R_g	Gate resistance	$f=1\text{MHz}$		7.2	9	Ω
SWITCHING PARAMETERS						
$Q_g(10\text{V})$	Total Gate Charge	$V_{GS}=-10\text{V}$, $V_{DS}=-30\text{V}$, $I_D=-4\text{A}$		16	20	nC
$Q_g(4.5\text{V})$	Total Gate Charge			8	10	nC
Q_{gs}	Gate Source Charge			2.5		nC
Q_{gd}	Gate Drain Charge			3.2		nC
$t_{D(on)}$	Turn-On Delay Time	$V_{GS}=-10\text{V}$, $V_{DS}=-30\text{V}$, $R_L=7.5\Omega$, GEN		8		ns
t_r	Turn-On Rise Time			3.8		ns
t_f	Turn-Off Fall Time			7.5		ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=-4\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		27	35	ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=-4\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		32		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any a given application depends on the user's specific board design. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C: The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JL}$ and lead to ambient.

D: The static characteristics in Figures 1 to 6, 12, 14 are obtained using 80 μs pulses, duty cycle 0.5% max.

E: These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The SOA curve provides a single pulse rating.

-60V P-Channel MOSFET

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

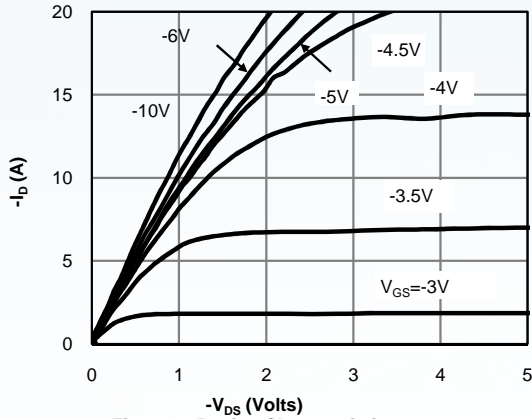


Fig 1: On-Region Characteristics

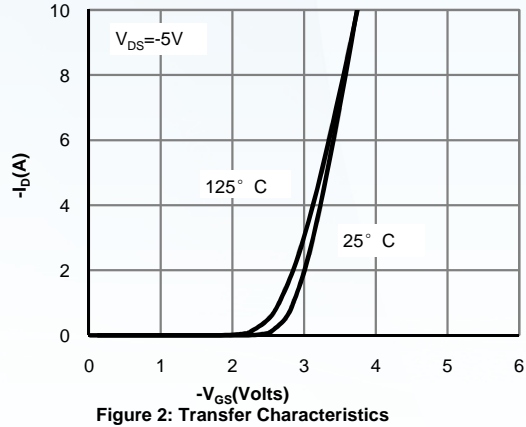


Figure 2: Transfer Characteristics

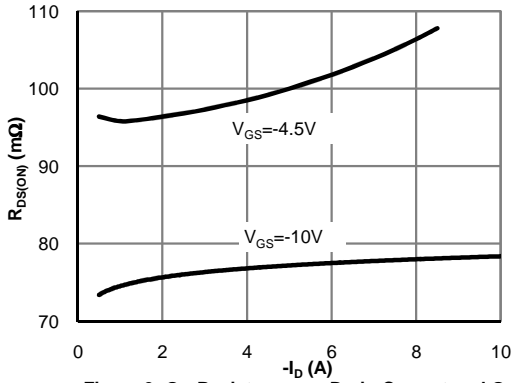


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

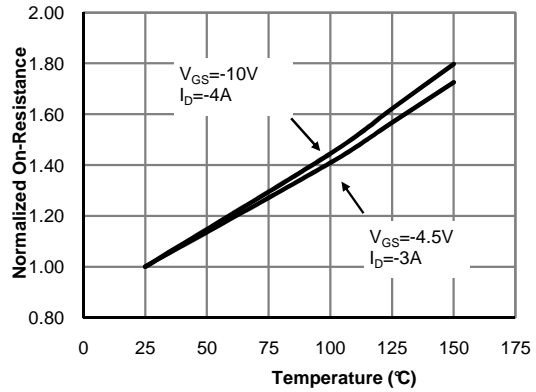


Figure 4: On-Resistance vs. Junction Temperature

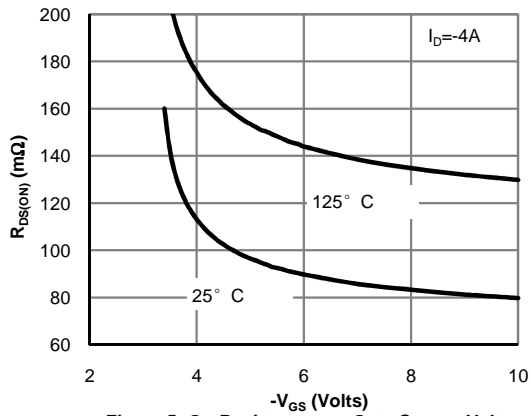


Figure 5: On-Resistance vs. Gate-Source Voltage

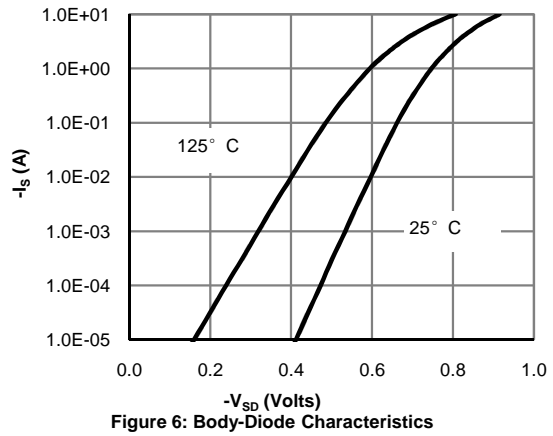


Figure 6: Body-Diode Characteristics

-60V P-Channel MOSFET

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

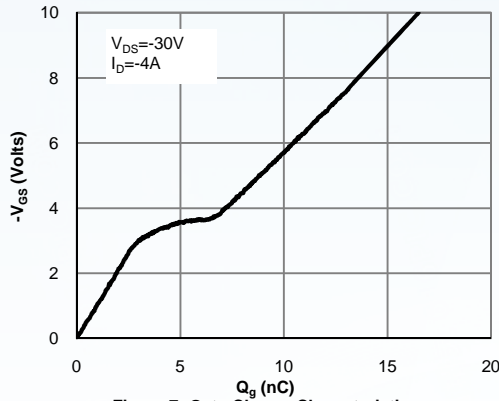


Figure 7: Gate-Charge Characteristics

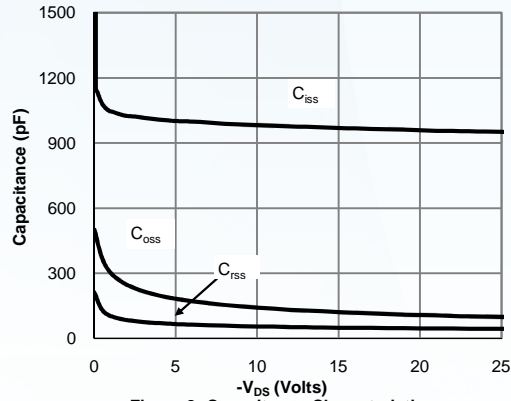


Figure 8: Capacitance Characteristics

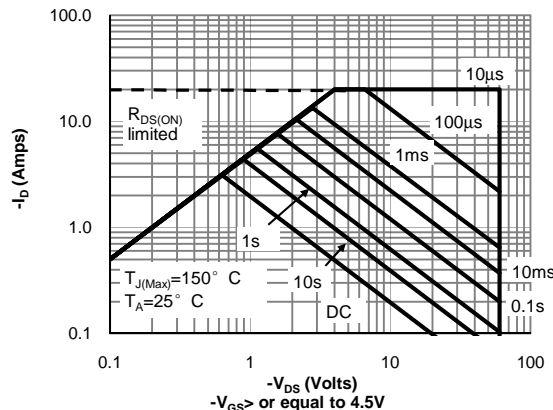


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

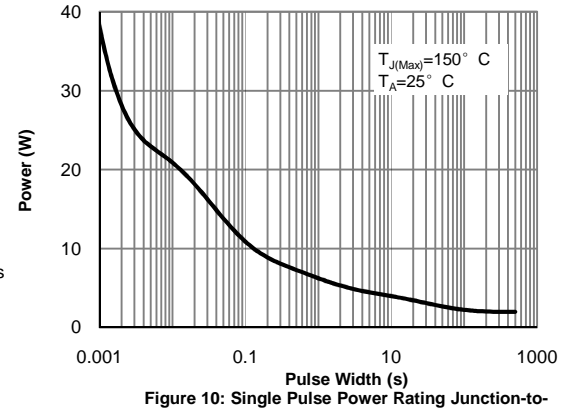


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

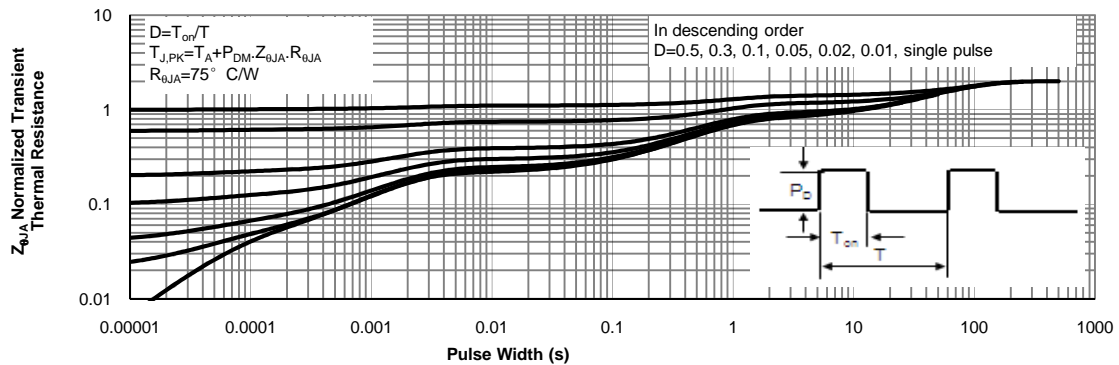
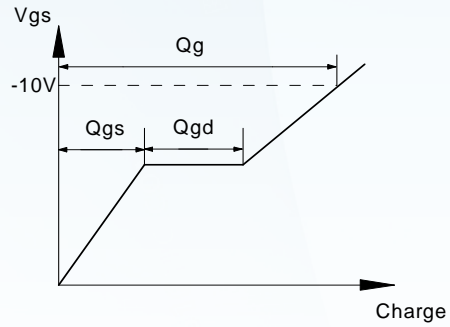
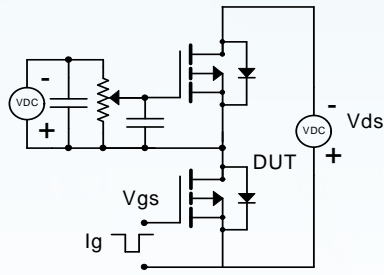


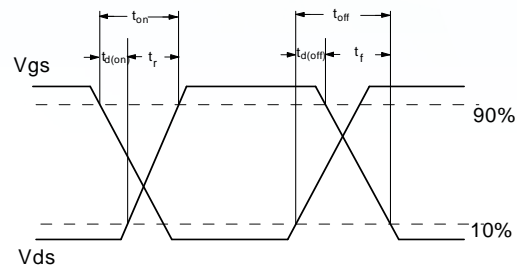
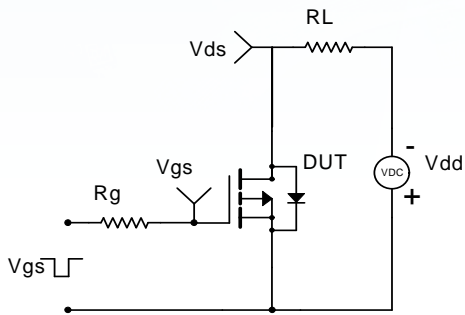
Figure 11: Normalized Maximum Transient Thermal Impedance

Gate Charge Test Circuit & Waveform

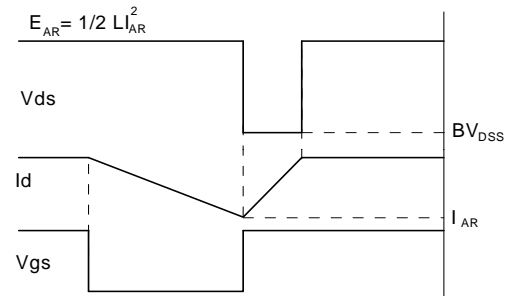
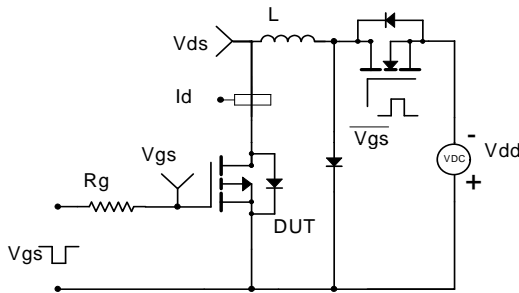
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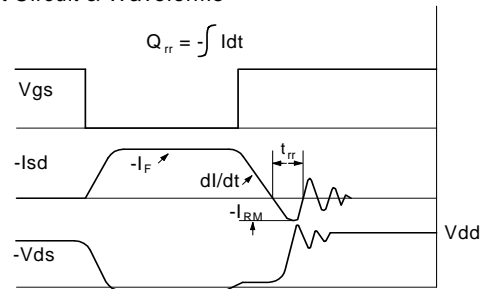
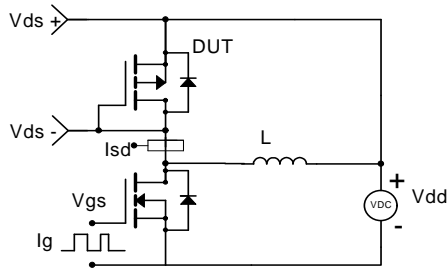
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



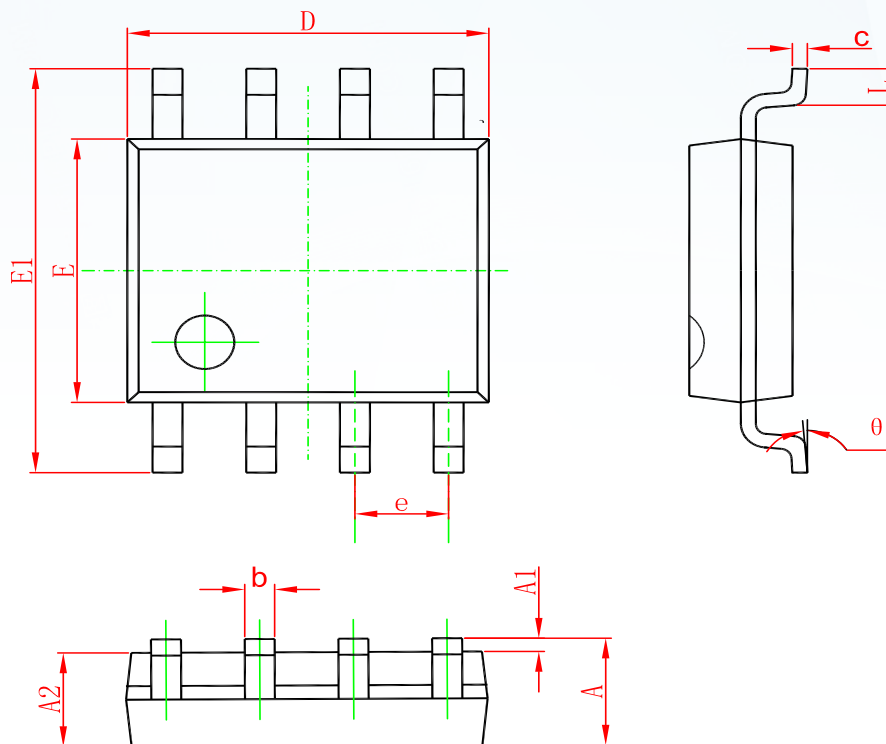
Diode Recovery Test Circuit & Waveforms



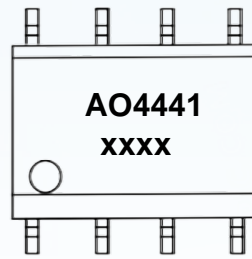
-60V P-Channel MOSFET

PACKAGE OUTLINE DIMENSIONS

SOP-8



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

-60V P-Channel MOSFET**Marking****Ordering information**

Order code	Package	Baseqty	Deliverymode
AO4441	SOP-8	3000	Tape and reel

Disclaimer

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